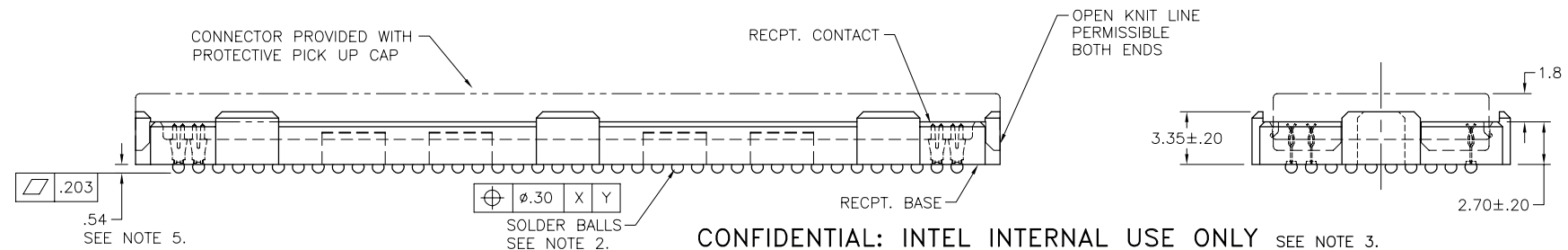
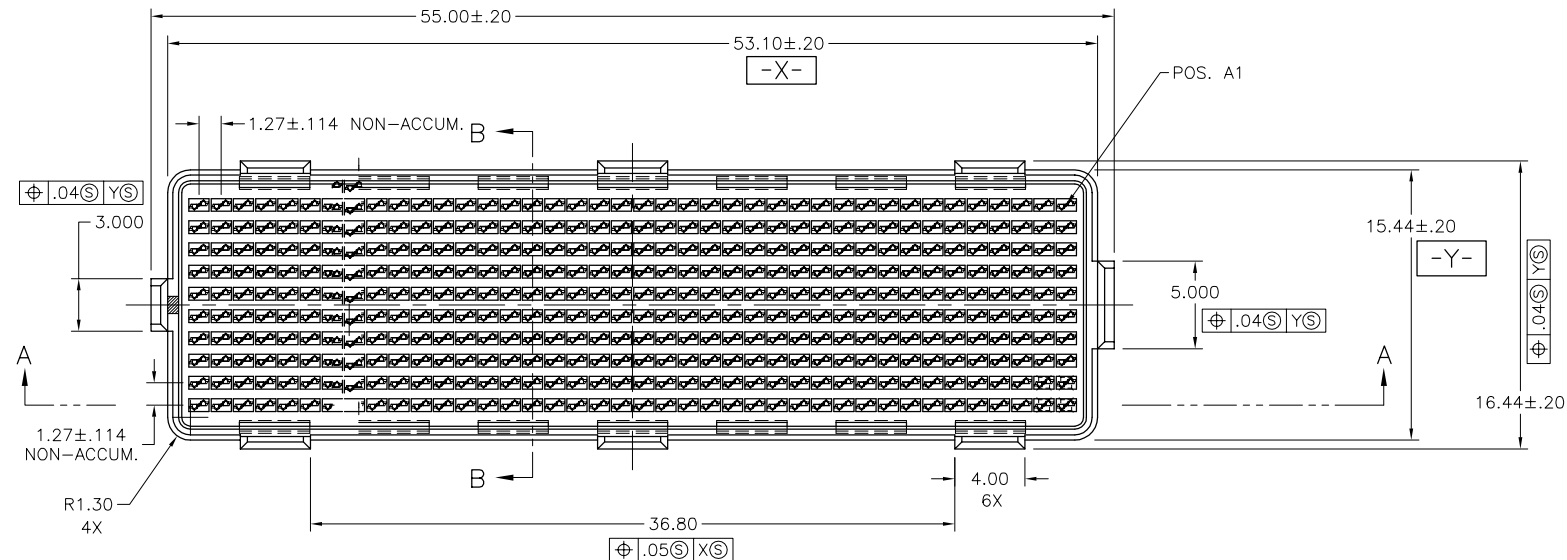


PRODUCT NO.	SOLDER BALL MATERIAL	CONTACT PLATING
74220-001	EUTECTIC SnPb	15-40u"/.38-1.02um Au
74220-001LF	SnAgCu LEAD FREE (6)(7)	OVER 30-120u"/.76-3.05um Ni

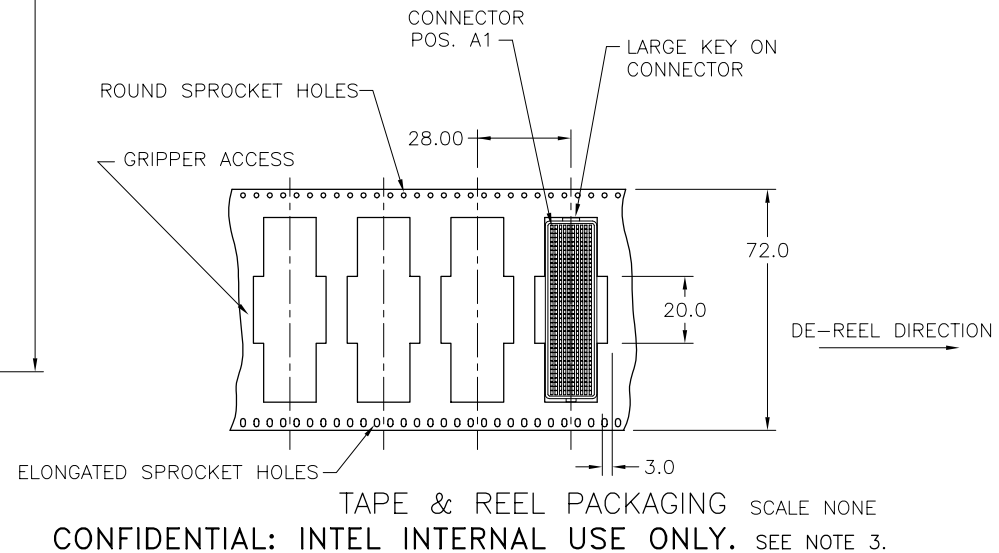
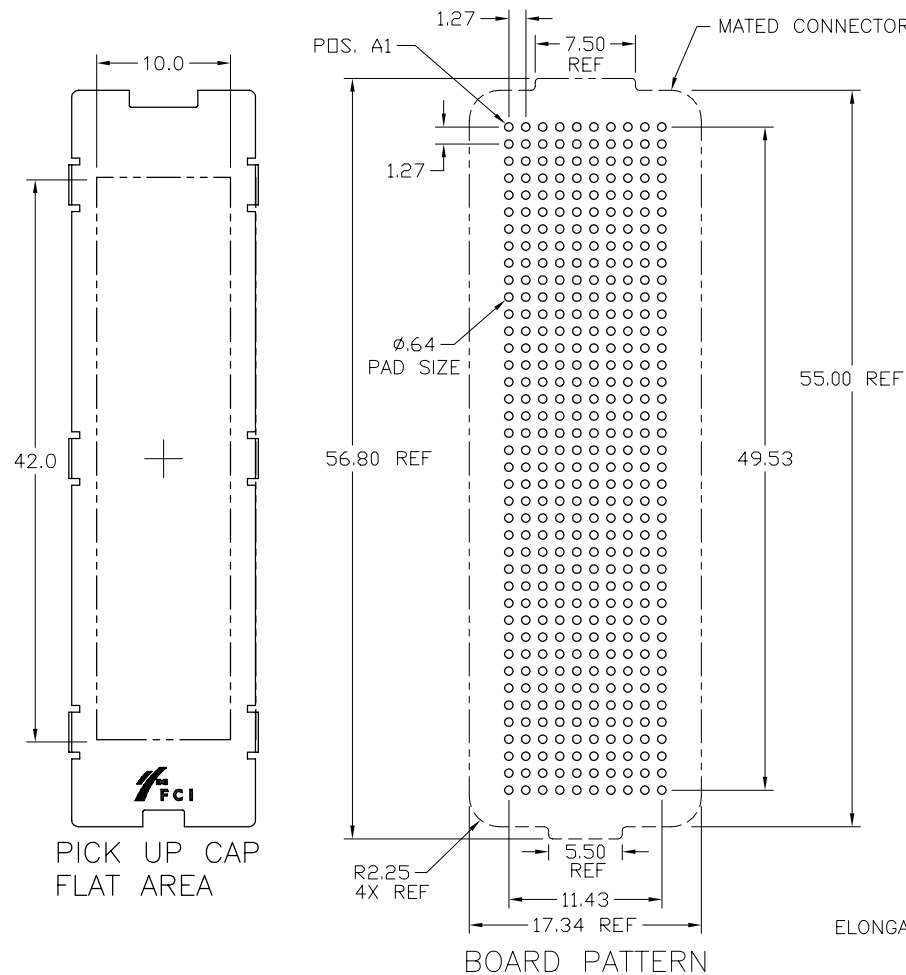


CONFIDENTIAL: INTEL INTERNAL USE ONLY SEE NOTE 3.

mat'l. code	SEE NOTE 1	surface	ASME Y14.5	tolerance	ASME Y14.5	projection	product family
ltr	ecr no	dr	date	tolerances unless otherwise specified			MEG-ARRAY
A	V71483	DRW	10-14-97	angles	X *3		
B	V80713	DRW	4.17.98	XX *13			
C	V81013	DRW	6.2.98	0° ±2'	XXX *051	scale 3:1	
D	V00181	HLJ	9.07.00	dr	M.J.WENDEL	970917	
E	V04-0940	VS	10/27/04	enr	T.LEMKE	10.14.97	
F	V05-1071	DAI	12/21/05	chr	T.LEMKE	10.14.97	
G	V06-0560	LP	2006/06/23	appd	T.LEMKE	10.14.97	
sheet	revision	G	G	G			
index	sheet	1	2	3			

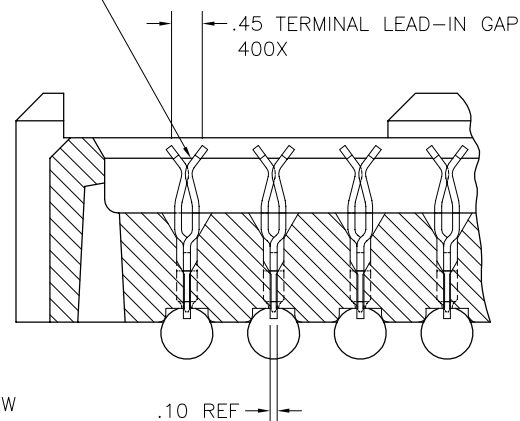
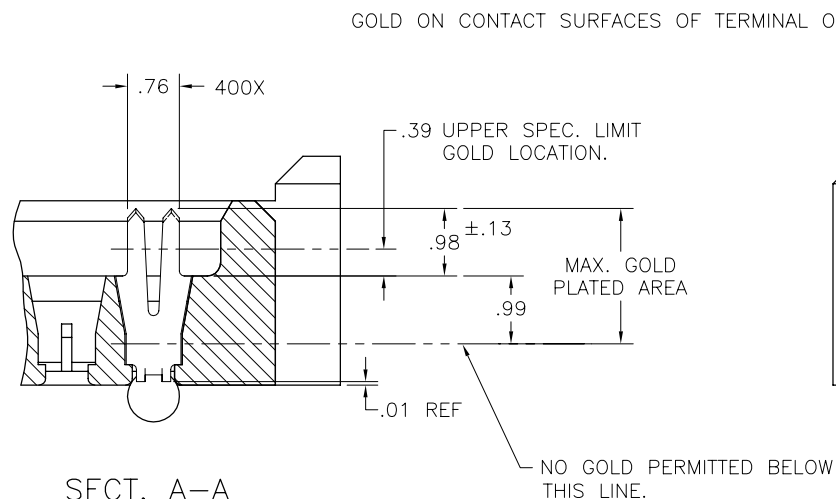


title	4mm RECPT. ASSY 10X40= 400 POS.
dwg no	74220
sheet	1 of 3
size	A4
type	CUSTOMER Drawing



CONFIDENTIAL: INTEL INTERNAL USE ONLY. SEE NOTE 3.

mat'l. code SEE NOTE 1				surface ASME Y14.5 ✓		tolerance ASME Y14.5	projection mm	product family MEG-ARRAY		
ltr	ecr no	dr	date	tolerances unless otherwise specified			mm	title		
g				angles	time	X *3		4mm RECPT. ASSY		
				0° ±2'		XX *13	scale 2:1	10X40= 400 POS.		
				dr	M.J.WENDEL	970917		dwg no		
				enr	T.LEMKE	10.14.97	FCI	sheet 2 of 3		
				chr	T.LEMKE	10.14.97		74220		
				appd	T.LEMKE	10.14.97	type	CUSTOMER Drawing		
sheet index	revision sheet									

**NOTES:****1. MAT'L:**

HOUSING: LCP (GRADE PROPRIETARY).

CONTACT: BeCu/C17200.

PLATING:

CONTACT: 15-40u"/.38-1.02um Au OVER 30-120u"/.76-3.05um Ni.

SOLDER BALL: (SEE TABLE ON SHEET1)

EUTECTIC SnPb OR LEAD FREE

95.5Sn/4Ag/0.5Cu

2. SOLDER BALLS WILL NOT BE PERFECT SPHERICAL SHAPE DUE TO REFLOW ATTACHMENT. NOMINAL INITIAL SOLDER BALL ϕ .76 (.030").
3. DRAWING NO. 74221 TO BE USED FOR INTEL CUSTOMERS (OEM).
4. REFER TO 07-747 INTEL PROCUREMENT SPEC.
5. SOLDER BALL HEIGHT TOLERANCE PENDING FINAL AGREEMENT.

6. FOR PROPER APPLICATION FOLLOW FCI APPLICATION SPECIFICATION GS-20-033 LEAD FREE SOLDER BALLS WILL NOT SOLDER PROPERLY IN A LEADED SOLDER PROCESS DUE TO A HIGHER REFLOW TEMPERATURE. LEAD FREE PRODUCT IS THEREFORE NOT BACKWARDS COMPATIBLE WITH LEADED OR SOME SOLDERING APPLICATIONS. REFERENCE FCI APPLICATION SPECIFICATION

7. THIS PRODUCT MEETS EUROPEAN UNION DIRECTIVES AND OTHER COUNTRY REGULATIONS AS DESCRIBED IN GS-22-008 PRODUCT MEETING THIS DIRECTIVE IS IDENTIFIED IN THE LOT CODE NUMBER MARKED ON EACH PART BY HAVING AN "X" IN THE SEVENTH CHARACTER POSITION

CONFIDENTIAL: INTEL INTERNAL USE ONLY SEE NOTE 3.

mat'l. code SEE NOTE 1				surface ASME Y14.5 ✓	tolerance ASME Y14.5	projection 	product family MEG-ARRAY			
ltr	ecr no	dr	date	tolerances unless otherwise specified			title 4mm RECPT ASSY 10X40= 400 POS.			
g				angles	line fit	mm				
				0° ±2°	X *3 XX *13 XXX *051	scale 10:1	dwg no 74220			
				dr	M.J.WENDEL 971013					
				enrg	T.LEMKE 10.14.97		sheet 3 of 3 size A4			
				chr	T.LEMKE 10.14.97					
				appd	T.LEMKE 10.14.97		type CUSTOMER Drawing			
sheet index	revision sheet									